

Docket No.: GR 97 P 2681

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Dm

jc526 U.S. PTO
09/164123
09/30/98

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : ALBRECHT MAYER
Filed : Concurrently herewith
Title : METHOD FOR ASSEMBLING INTEGRATED CIRCUITS WITH
PROTECTION OF THE CIRCUITS AGAINST ELECTROSTATIC
DISCHARGE, AND ARRANGEMENT OF INTEGRATED
CIRCUITS WITH PROTECTION AGAINST ELECTROSTATIC
DISCHARGE

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or
publications are submitted herewith:

U.S. Patent No. 5,587,598 (Hatanaka), dated December 24, 1996;

East German Patent No. DD 236 623 B5 (Seidel et al.), dated June 11, 1986, hybrid
circuit protected against electrostatic discharge or contact voltages.

If no translation of pertinent portions of any foreign language patents or publications
mentioned above is included with the aforementioned copies of those applications,
patents and/or publications, it is because no existing translation is readily available
to the applicant.

Respectfully submitted,


For Applicant

VERNER H. STEMER
REG. NO. 34,956

Date: September 30, 1998

Lerner and Greenberg, P.A.
Post Office Box 2480
Hollywood, FL 33022-2480
Tel: (954) 925-1100
Fax: (954) 925-1101
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